



Material Content Data Sheet



Sales Product Name		BSC040N08NS5		Issued		30. July 2019		
MA#		MA004038194						
Package		PG-TDSON-8-50		Weight*		106.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.096	1.03	1.03	10257	10257
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		510	
	non noble metal	iron	7439-89-6	1.090	1.02		10202	
wire	non noble metal	copper	7440-50-8	44.271	41.42	42.50	414263	425103
	noble metal	gold	7440-57-5	0.042	0.04	0.04	395	395
	encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		789
plastics	plastics	epoxy resin	-	3.878	3.63		36287	
	inorganic material	silicondioxide	60676-86-0	38.189	35.74	39.45	357352	394428
	leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11825
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	271	271
solder	noble metal	silver	7440-22-4	0.038	0.04		359	
	non noble metal	tin	7440-31-5	0.077	0.07		718	
	non noble metal	lead	7439-92-1	1.420	1.33	1.44	13284	14361
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		172	
	non noble metal	iron	7439-89-6	0.368	0.34		3441	
	non noble metal	copper	7440-50-8	14.930	13.97	14.33	139704	143360
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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